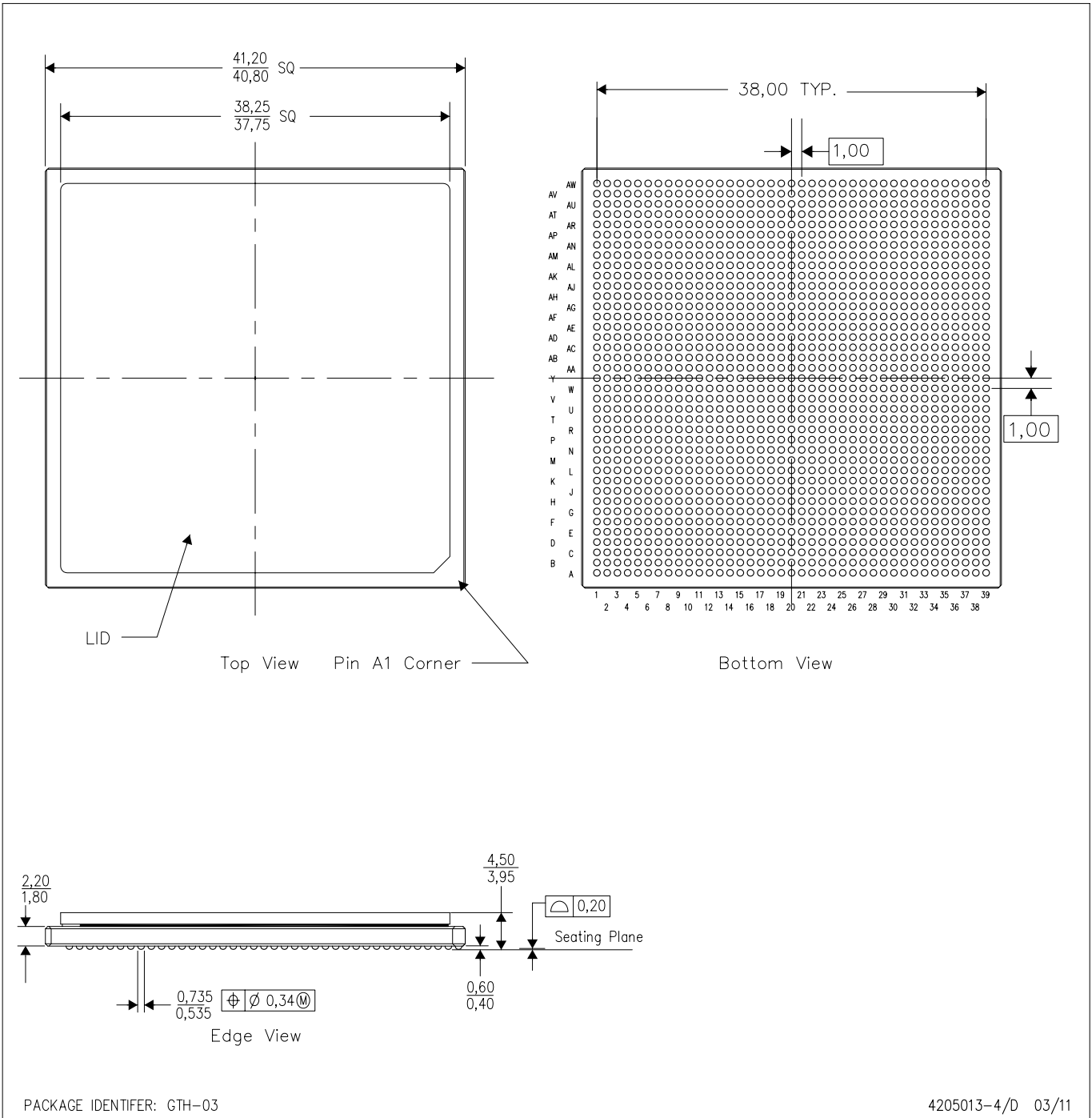


MECHANICAL DATA

GTH (S-CBGA-N1521)

CERAMIC BALL GRID ARRAY



- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Thermally enhanced ceramic package with a lid.
 - Flip chip application only.

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